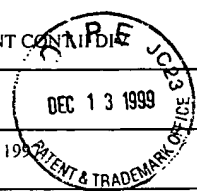
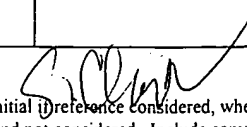
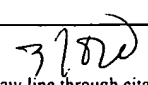
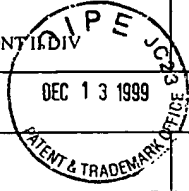



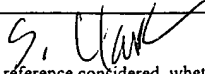



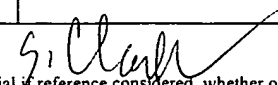


FORM PTO-1449 (Rev. 7-80)		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. TESSERA 3.3-018 CONT		Application No. 08/984,615	
LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)				Applicant <i>Khandros, et al.</i>			
				Filing Date: December 3, 1999			
U.S. PATENT DOCUMENTS							
*EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
SLC	AA	4,961,105	10/2/90	<i>Yamamoto</i>	357	72	
SLC	AB	5,216,278	6/1/93	<i>Lin et al</i>	257	688	
SN	AC	5,241,133	8/31/93	<i>Mullen, III et al.</i>	174	52.4	
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
SLC	AL	JP 63-290796	11/28/88	Japan			X
SLC	AM	JP 63-51196	3/4/88	Japan			X
SLC	AN	JP 63-290795	11/28/88	Japan			X
SLC	AO	JP 2-128453	5/16/90	Japan			X
	AP						
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
SLC	AR	JP 63-290796, copy including annotations					
SLC	AS	JP 63-51196, copy including annotations					
SN	AT	JP 63-290795, copy including annotations					
EXAMINER				DATE CONSIDERED			
							
<small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>							

FORM PTO-1449 (Rev. 7-80)		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. TESSERA 3.3-018 CONT CONT		Application No. 08/984,615	
LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)				Applicant Khandros, et al.		<div style="border: 1px solid black; border-radius: 50%; padding: 5px; text-align: center;"> DEC 13 1999 U.S. PATENT & TRADEMARK OFFICE </div>	
				Filing Date: December 3, 1997			
U.S. PATENT DOCUMENTS							
*EXAMINER INITIALS		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
	AL						
	AM						
	AN						
	AO						
	AP						
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
gjk	↓ AR	JP 2-128453, copy including annotations					
gjk	↓ AS	1987 Proceedings 37 th Electronic Components Conference, May 11-13, 1987, Die Attachment Design and Its Influence on Thermal Stresses in the Die and the Attachment, E. Suhir, pages 508-517					
gjk	↓ AT	Electronic Components Conference 33 rd , May 16-18, 1983, The Quality of Die-Attachment and Its Relationship to Stresses and Vertical Die-Cracking, C.G.M. van Kessel, S.A. Gee and J.J. Murphy, pages 237-244					
EXAMINER				DATE CONSIDERED			
S. Clark				3/80			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

FORM PTO-1449 (Rev. 7-80)		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. TESSERA 3.3-018 CONT COPY		Application No. 08/984,615	
LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)				Applicant <i>Khandros, et al.</i>		<div style="border: 1px solid black; border-radius: 50%; padding: 5px; display: inline-block;"> DEC 13 1999 U.S. PATENT & TRADEMARK OFFICE </div>	
				Filing Date: December 3, 1999			
U.S. PATENT DOCUMENTS							
*EXAMINER INITIALS		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
							YES NO
	AL						
	AM						
	AN						
	AO						
	AP						
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
SVC	✓ AR	Electronic Components Conference 34 th , May 14-16, 1984, Die Attach in Hi-Rel P-Dips: Polyimides or Low Chloride Epoxies?, Justin C. Bolger and Charles T. Mooney, pages 63-67					
SVC	✓ AS	Ablebond® 84-3 MV, Electrically Insulating Epoxy Adhesive, 12/97					
SVC	✓ AT	Ablebond® 84-3 MV, One Component, Insulative Chip Adhesive, 11/97					
EXAMINER <i>S. Clark</i>				DATE CONSIDERED <i>3/00</i>			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

FORM PTO-1449 (Rev. 7-80)		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. TESSERA 3.3-018 CONT CONT DIV		Application No. 08/984,615	
LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)				Applicant <i>Khandros, et al.</i>			
				Filing Date: December 3, 1997			
U.S. PATENT DOCUMENTS							
*EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
	AL						
	AM						
	AN						
	AO						
	AP						
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
	✓ AR	Ablebond® 84-3MV, Electrically Insulating Chip Adhesive, Rev. 6/90					
	✓ AS	Ablestik®, One Component, Insulating Chip Adhesive, Rev. 2/88					
	✓ AT	Microelectronics Packaging Handbook. Rao R. Tummala. Eugene J. Rymaszewski, pages 312-320, (1989).					
EXAMINER					DATE CONSIDERED		
							
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>							

FORM PTO-1449 (Rev. 7-80)		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. TESSERA 3.3-018 CONT CONT II DIV		Application No. 08/984,615	
LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)				Applicant Khandros, et al.			
				Filing Date: December 3, 1997		Group 2815	
U.S. PATENT DOCUMENTS							
EXAMINER INITIALS		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
	AL						YES NO
	AM						
	AN						
	AO						
	AP						
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
	AR	"No Stress" Dielectric Epoxy Adhesives with High Thermal Conductivity, date unknown.					
	AS						
	AT						
EXAMINER 				DATE CONSIDERED 3/00			
<small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>							
<small>232729_1.DOC</small>							